## **AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) An online entrusting system for a semiconductor package comprises:

a processing controllermanage and control unit to process an semiconductor package order inputted by a user via an interface of internet, wherein said order includes a required requiring information selected from at least one information of a substrate, a die dimension, a package type, a thermal performance, an amount of substrate layers, numbers of input terminals and output terminals, and pitches between said input and output terminals about said semiconductor package;

a database coupled to said processing controllermanage and control unit to store said required requiring information and a schedule information;

a plurality of <u>analysis</u>analyzing modules coupled to said <u>processing controllermanage and</u>
<u>control unit</u> to produce an analysis result about said <u>required</u>requiring information <u>being attained</u>
<u>or not</u>; and

a reply<del>ing</del> means responding said analysis result of said <u>analysis</u> analyzing modules to said user.

## 2-9. (Cancelled)

10. (Currently Amended) The system of claim 1, wherein said schedule information includes athe progress information about processing said order and athe result for processing said order.

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11. (Currently Amended) The system of claim 1, wherein said plurality of

analysisanalyzing modules are selected from at least one of include athe thermal analysis

module, a circuit analysis module, a stress analysis module, a reliability analysis module, a

material analysis module and a substrate analysis module.

12. (Currently Amended) A method for automatically providing online package

entrusting comprises:

inputting an required requiring information about a semiconductor package by a user via

an internet, wherein said required information is selected from at least one information of a

substrate, a die dimension, a package type, a thermal performance, an amount of substrate layers,

numbers of input terminals and output terminals, and pitches between said input and output

terminals about said semiconductor package;

storing said required requiring information in a database;

producing a plurality of analysis results by a plurality of analysis modules according to

said requiredrequiring information of said order;

recording said analysis results in said database; and

responding said analysis results to said user by a reply<del>replying</del> means.

13-19. (Cancelled)

20. (Currently Amended) The method of claim 12, wherein said plurality of

analysisanalyzing modules are selected from at least one of include athe thermal analysis

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module, <u>a</u> circuit analysis module, <u>a</u> stress analysis module, <u>a</u> reliability analysis module, <u>a</u> material analysis module and <u>a</u> substrate analysis module.